

IMPACT-EMAP 2014 Call for Papers

Submit Your Abstract Before June 15!

Accepted Papers Will Be Collected in IEEE Xplore!

International Microsystems, Packaging, Assembly and Circuits Technology Conference—IMPACT 2014 calls for paper now! This year, the 16th EMAP (International Conference on Electronics Materials and Packaging) is rotated in Taiwan and joined with IMPACT 2014. The IMPACT Conference is the largest gathering of packaging and PCB professionals in Taiwan, attracting over 3,600 attendees in accumulated total over the past few years. Do you have any new discovery or stunning research? Summit your paper to IMPACT-EMAP 2014 conference before June 15th immediately. It is truly your best access and practice to this new paradigm shift.

IMPACT-EMAP 2014 which is jointly organized by IEEE CPMT-Taipei, iMAPS-Taiwan, ITRI and TPCA, and co-organized by ISU, NK, NTU, SMTA and TTMA, and keeps collaborating with International organizations such as ICEP from Japan and iNEMI from USA. Like last year, IMPACT-EMAP 2014 will be held in conjunction with TPCA Show on Oct. 22-24, 2014, at Taipei Nangang Exhibition Center.

Consumer Electronics Association (CEA) identifies the five tech trends for 2014: the Internet of Things (IoT), driverless cars, digital health care, robotics and content curation. The research report shows their potential to enrich our lives, and in some cases, massively change them. To reflect the cutting-edges technology development, the theme of IMPACT-EMAP 2014 highlights “Challenge for Change-Shaping the Future” and will arrange keynote speeches, invited talks, industrial sessions and outstanding paper presentations.

The IMPACT Conference is an amazing convergence of microsystems knowledge and community via bridging the industries and academia. IMPACT is committed to helping you fulfill your increasingly demanding role in the R&D department as well as provide more contents for your needs and goals! Researchers in academia, industries and research institutes, submit your paper before June 15. Your participation is a key to cross-domain communication and inter-field innovation; with your support, this conference is believed to become an important and valuable resource.

Call for Paper

Conference: IMPACT-EMAP 2014 (The 9th IMPACT and 16th EMAP Joint Conference)

Exhibition: TPCA Show 2014

Theme: **Challenge for Change-Shaping the Future**

Date: Oct 22 (Wed)-24(Fri), 2014

Venue: Taipei Nangang Exhibition Center

On-line Submission: www.impact.org.tw

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	June 15, 2014	400-500 words Submit on-line through conference website
Abstract Acceptance Notification	July 14, 2014	Notice sent via email
Online Registration Opens	July 28, 2014	
Advance Program Online	August 11, 2014	Advanced program announcement
Full Paper Submission (Camera-ready Version)	August 15, 2014	4 pages including figures and tables Submit on-line through conference website and copyright forms due

* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.

* The secretariat keeps the right to modify the agenda.

SCOPE OF PAPER SOLICITED

IMPACT

Packaging

PCB

P1 -Advanced Packaging Technologies

B1. Green Materials and Process

P2. Green Packaging

B2. Test, Quality, Inspection and Reliability Technology

P3-3D Integration

B3. HDI and Embedded Technology

P4-LED & Optoelectronics Packaging

B4. Electro Deposition and Electrochemical Processing
Technology

P5-Interconnections & Nanotechnology

B5. Advanced and Emerging Technology

P6-Modeling, Simulation & Design

B6. Mechatronics and Automation

P7-Thermal Management

B7. Marketing & Management

P8- Advanced Sensor & Microsystems Technology (MST)

P9-Advanced Materials, Automatic Process & Assembly

P10-Emerging Systems Packaging Technologies

EMAP

Materials and Packaging

M1. Materials and Processing

M2. Passive and Active Components

M3. Optoelectronics / Photonics

M4. Sensor, Actuator, and Transducer Technologies

M5. Advanced Packaging

M6. Thru Silicon Via (TSV) Technology

M7. Interconnection Technologies

M8. System-in-Package (SiP) and 3D Stacked Die Packaging

M9. Electrical Modeling, Characterization, and Signal
Integrity

M10. Thermal-Mechanical Modeling and
Characterization

M11. Quality and Reliability

M12. Packaging Technologies for High Brightness LEDs

M13. Flexible Electronics

M14. Others

* Papers relevant with the above scopes are encouraged to submit but NOT limited to.

* Conference authority keeps the right to final session arrangement.

PAPER AWARD

Best Student Paper Award and Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored at the conference.

SPONSOR

IMPACT 2014 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

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INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY -TAIWAN (IMAPS-Taiwan)

INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE, TAIWAN (ITRI)

TAIWAN PRINTED CIRCUIT ASSOCIATION (TPCA)

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